



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-03-08
Contact Name *	Refer to Supplier comment section	Contact Title	Refer to Supplier comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement


Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	22BA*MV3WBAA	B	MA1A	2018-03-08
Amount	UoM	Unit type	ST ECOPACK Grade	
8.5	mg	Each	ECOPACK® 2	
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Gold (Ni/Au), electrolytic	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
LGA	2x2x1	12	No lead	
Comment	A0K6 VFLGA 2X2X1 12LD PITCH 0.5MM; MDF valid for LIS2HH12TR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description
7c-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices

QueryList : REACH-17th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	228A*MV3WBAA									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Dies	Other inorganic materials	3.067	mg	supplier	die	Silicon (Si)	7440-21-3		2.828	mg	922074	332706				
				supplier	metallisation	Aluminium (Al)	7429-90-5		0.007	mg	2282	824				
				supplier	metallisation	Copper (Cu)	7440-50-8		0.017	mg	5543	2000				
				supplier	metallisation	Tantalum (Ta)	7440-25-7		0.003	mg	978	353				
				supplier	metallisation	Titanium (Ti)	7440-32-6		0.002	mg	652	235				
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.006	mg	1956	706				
				supplier	passivation	Silicon Oxide	7631-86-9		0.034	mg	11086	4000				
				JIG - R	die glass coating	Lead-Borate Glass	65997-18-4	7c-1-Electrical and electron	0.170	mg	55429	20000				
				substrate	Other Organic Materials	1.698	mg	supplier	core material	Bismaleimide (B)	105391-33-1		0.114	mg	67141	13412
								supplier	core material	Triazine (T)	25722-66-1		0.114	mg	67141	13412
supplier	core material	Fiber glass	65997-17-3						0.339	mg	199656	39882				
supplier	core material	Thermosetting resin	54208-63-8						0.190	mg	111902	22353				
supplier	core material	metal hydroxide	21645-51-2						0.008	mg	4712	941				
supplier	core material	Calcium sulfate	7778-18-9						0.004	mg	2356	471				
supplier	core material	Zinc hydroxide	20427-58-1						0.002	mg	1178	235				
supplier	Solder mask	Barium sulfate	7727-43-7						0.010	mg	5890	1176				
supplier	Solder mask	Acrylic resin	9003-01-4						0.016	mg	9423	1882				
supplier	Solder mask	Epoxy resin	29690-82-2						0.013	mg	7656	1529				
supplier	Solder mask	Biphenyl epoxy resin	85954-11-6						0.008	mg	4712	941				
supplier	Solder mask	Talc containing no asbestiform fibers	14807-96-6						0.006	mg	3534	706				
supplier	Solder mask	Methoxymethylethoxy propanol	34590-94-8						0.002	mg	1178	235				
supplier	Solder mask	Amorphous silica	7631-86-9						0.001	mg	589	118				
supplier	Solder mask	3-methyl-methoxy-butyl	103429-90-9						0.001	mg	589	118				
supplier	Solder mask	Silica Cristobalite	14464-46-1						0.001	mg	589	118				
	Copper & Its alloys							supplier	metallisation	Copper (Cu)	7440-50-8		0.859	mg	506137	101103
								supplier	metallisation	Nickel (Ni)	7440-02-0		0.008	mg	4947	988
								supplier	metallisation	Gold (Au)	7440-57-5		0.001	mg	671	134
Die attach	Other Organic Materials	0.165	mg					supplier	tape	epoxy resin	Proprietary		0.105	mg	636364	12353
				supplier	tape	polyolefin	9003-07-0		0.052	mg	315152	6118				
				supplier	tape	Diphenol Propane Diglycidyl Ether	1675-54-3		0.008	mg	48485	941				
Bonding wire	Precious metals	0.153	mg	supplier	wire	Gold (Au)	7440-57-5		0.153	mg	1000000	18000				
encapsulation	Other Organic Materials	3.418	mg	supplier	mold compound	Silica, vitreous	60676-86-0		2.958	mg	865418	348000				
				supplier	mold compound	Epoxy Resin	85954-11-6		0.137	mg	40082	16118				
				supplier	mold compound	Phenol Resin	26834-02-6		0.137	mg	40082	16118				
				supplier	mold compound	Epoxyde Bisphenol A Resin	25068-38-6		0.103	mg	30135	12118				
				supplier	mold compound	Aluminium hydroxyde	21645-51-2		0.068	mg	19895	8000				
				supplier	mold compound	Carbon black	1333-86-4		0.015	mg	4389	1765				